



Product Change Notification

Change Notification #: 118930-00
Change Title: Intel® Server System D50TNP1MHCRCAC Compute Module, PCN 118930-00, Product Design, DIMM Slot Connector Replacement
Date of Publication: March 02, 2022

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	March 17, 2022
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is replacing the DIMMs slot connectors by a second source to meet with RoHS and Halogen free regulatory requirements. The new DIMMs slots connectors are identical in function, size and form to the previous one.

Customer Impact of Change and Recommended Action:

Intel® does not expect any impact to customers from this change but encourages customers to understand the change and determine the impact on their applications. For that reason, Intel recommends that the customer perform a standard level of evaluation.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
Intel® Server System D50TNP1MHCRCAC Compute Module , Single	D50TNP1MHCRCAC	99A84D	M39438-002	M12931-151	M39438-003	M12931-152

PCN Revision History:

Date of Revision: March 02, 2022	Revision Number: 00	Reason: Originally Published PCN
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Product Change Notification

118930-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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